

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A method of Method for producing fully ceramic tooth elements having a pre-determined spatial form by means of electrophoresis, comprising: characterized in that  
arranging an electrically conductive chip, or a chip which has been rendered electrically conductive, is arranged directly on a working model or on a part of a [[the]] framework, and whereby  
conducting electrophoresis,  
wherein the chip comprises ~~can comprise~~ regions of different electrical conductivity,  
wherein stronger electrical currents in regions of higher electrical conductivity provide increased deposition of a framework material in comparison to regions of lower electrical conductivity, such that the framework material is provided in a desired shape,  
wherein the chip [[and]] is connected preferably to a [[the]] positive pole during [[the]] electrophoresis.
2. (Currently Amended) A method Method according to Claim 1, wherein characterized in that the framework material is [[being]] deposited.
3. (Currently Amended) A method Method according to Claim 1, wherein characterized in that a veneering material is [[being]] deposited.
4. (Currently Amended) A method Method according to Claim 1, wherein characterized in that the chip is a synthetic paper made electrically conductive by means of a salt solution.
5. (Currently Amended) A method Method according to Claim 1, wherein characterized in that the areas regions of lower electrical resistance are provided by generated by means of aluminum foil.
6. (Currently Amended) A method Method according to Claim 2, wherein characterized in that an alumina or zirconia slip is used in the method.

7. (Currently Amended) A method ~~Method~~ according to Claim 4, wherein the chip is made of nylon ~~characterized in that nylon is used as the chip material.~~
8. (Currently Amended) A method ~~Method~~ according to Claim 1, wherein ~~characterized in that the chip comprises alumina fibers, in particular whiskers.~~
9. (Currently Amended) A method ~~Method~~ according to Claim 1, wherein the chip comprises ~~characterized in that an electrically conductive foil, e.g. made of aluminum, is arranged between two fibrous layers of the chip.~~
10. (Currently Amended) A method ~~Method~~ according to Claim 9 ~~[[1]]~~, wherein ~~characterized in that the chip is made electrically conductive by a means of saline solution.~~
11. (Currently Amended) A method ~~Method~~ according to Claim 1, wherein ~~characterized in that the chip has a T-shaped cross-section.~~
12. (Currently Amended) A method ~~Method~~ according to Claim 1, wherein ~~characterized in that the chip is wider in a [[the]] middle of the chip than in an [[the]] area of [[the]] dies used in the method.~~
13. (New) A method according to claim 8, wherein the alumina fibers comprise whiskers.
14. (New) A method according to claim 9, wherein the electrically conductive foil is made of aluminum.
15. (New) A method according to claim 1, wherein at least a portion of an outside surface of the chip is insulated.
16. (New) A method according to claim 1, wherein the chip comprises a first electrically conductive layer, an electrically non-conductive layer, and a second electrically conductive layer,  
wherein the electrically non-conductive layer is arranged between the first and second electrically conductive layers.

17. (New) A method according to claim 16, wherein one of the first and second electrically conductive layers covers only portions of the electrically non-conductive layer to provide the regions of higher electrical conductivity.

18. (New) A method according to claim 1, wherein the chip is not consumed during electrophoresis.

19. (New) A method according to claim 1, wherein the chip comprises a plurality of metallic strips, wherein at least one strip is wider than other strips.

20. (New) An electrophoresis process for producing ceramic tooth elements with a predetermined spatial form, comprising:

    providing an electrically conductive chip, wherein the chip comprises regions of relatively low electrical conductivity and regions of relatively high electrical conductivity, and

    conducting electrophoresis to deposit a framework material,

    wherein the regions of relatively high electrical conductivity provide an increased amount of deposited framework material at the regions of relatively high electrical conductivity, while the regions of relatively low electrical conductivity provide a lesser amount of deposited framework material than the regions of relatively high electrical conductivity.